

Request form for confidential HITAG documents



NXP Semiconductors (founded by Philips)

To: Document Control Officer		NXP Semiconductors Austria GmbH Styria	
Mikron-Weg 1, A-8101 Gratkorn, Austria		Fax: +43 3124 299 124 Email: nxp.docu-control@nxp.com Date:	
From: Please note: passwords cannot be provided if data is not typed or missing			
Person's name:	Company's name:	Fax:	e-mail:
Project information: (Please provide additional project information for which HITAG product documentation is required):			

Dear NXP Document Control Officer, please send the documents of the following HITAG products to my address as stated above.

HITAG μ Documentation			Comment
<input type="checkbox"/>	HITAG μ : HITAG μ Transponder IC, Product datasheet		Doc: 1529**
HITAG S Documentation			Comment
<input type="checkbox"/>	<input type="checkbox"/>	HITAG S: HTSICH56/HTSICH48 transponder IC	Doc: 0792**
	<input type="checkbox"/>	HITAG S: HTSFCH56/HTSFCH48 Flip chip package specification	Doc: 0791**
	<input type="checkbox"/>	HITAG S: HTSH5601ETK/HTSH4801ETK HVSON2 package specification	Doc: 1071**
	<input type="checkbox"/>	HITAG S: HTSICH56/HTSICH48 bumped wafer specification	Doc: 0790**
	<input type="checkbox"/>	HITAG S: HTSICH56/HTSICH48 Transponder IC, Megabumped wafer specification	Doc: 1458**
HITAG 2 Documentation			Comment
<input type="checkbox"/>	<input type="checkbox"/>	HITAG 2: HT 2 transponder family - Communication protocol, reader vs. HITAG 2 transponder	Doc: 0386**
	<input type="checkbox"/>	HITAG 2: HT2DC20S20 transponder IC	Doc: 0298**
	<input type="checkbox"/>	HITAG 2: HT2ICS2002 Wafer specification	Doc: 0531**
	<input type="checkbox"/>	HITAG 2: HT2MOA2S20 Contactless chip card module specification	Doc: 0340**
HITAG 1 Documentation			Comment
<input type="checkbox"/>	<input type="checkbox"/>	HITAG 1: HT 1 transponder family - Communication protocol, reader vs. HITAG 1 transponder	Doc: 0385**
	<input type="checkbox"/>	HITAG 1: HT1ICS3002 Wafer specification	Doc: 0530**

I accept that NXP Semiconductors has the right to reject this request without giving reasons. I understand and accept that the CONFIDENTIAL marked documents are confidential and that I will handle those according to the following provisions:

1. Recipient undertakes not to disclose any data and information of the above mentioned documents, which Recipient has received or will receive – in whatsoever form – from NXP to any third party.
2. Recipient and NXP agree that the above stated obligations under this Agreement shall not apply to any data and information which, shown by documented proof, (a) now are or later enter the public domain, (b) Recipient receives from a third party without breach of a confidentiality obligation, or (c) were at the time of disclosure already in the possession of Recipient.
3. In respect of the disclosed data and information NXP reserves right and title to apply for juridical protection. The disclosure for the Recipient does not imply any right or title to apply for a protection on its side. The disclosure does not include the granting of any licence.
4. Recipient is responsible that its employees – as far as they are getting knowledge of the received data and information or having the possibility to get to know them – are or shall be committed according to these provisions respectively. The obligations of Recipient under this Agreement remain, however, untouched therefrom.
5. Recipient agrees to promptly return to NXP on demand any data and information which were furnished under this Agreement in written or any other material form, without retaining any copies.

Signature

Place, Date